# Gap Pad® I500

#### Thermally Conductive, Un-Reinforced Gap Filling Material

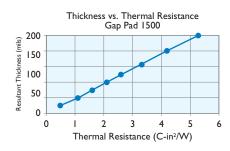
#### **Features and Benefits**

- Thermal conductivity: 1.5 W/m-K
- Un-reinforced construction for additional compliancy
- Conformable, low hardness
- · Electrically isolating



Gap Pad 1500 has an ideal filler blend that gives it a low-modulus characteristic that maintains optimal thermal performance yet still allows for easy handling. The natural tack on both sides of the material allows for good compliance to adjacent surfaces of components, minimizing interfacial resistance.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 1500					
PROPERTY	IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
Color	Black	Black		Visual	
Reinforcement Carrier	_	_		_	
Thickness (inch) / (mm)	0.020 to 0.200	0.508 to 5.080		ASTM D374	
Inherent Surface Tack (1 sided)	2	2		_	
Density (Bulk Rubber) (g/cc)	2.1	2.1		ASTM D792	
Heat Capacity (J/g-K)	1.0	1.0		ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (1)	40	40		ASTM D2240	
Young's Modulus (psi) / (kPa) (2)	45	310		ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200			
ELECTRICAL					
Dielectric Breakdown Voltage (Vac)	>6000	>6000		ASTM D149	
Dielectric Constant (1000 Hz)	5.5	5.5		ASTM D150	
Volume Resistivity (Ohm-meter)	1011	1011		ASTM D257	
Flame Rating	V-O	V-O		U.L. 94	
THERMAL					
Thermal Conductivity (W/m-K)	1.5	1.5		ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN					
	Deflection (% strain)		10	20	30
Thermal Impedance (°C-in²/W) 0.040" (3)			1.62	1.50	1.33
1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain					

with a sample size of 0.79 inch<sup>2</sup>. 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

#### **Typical Applications Include:**

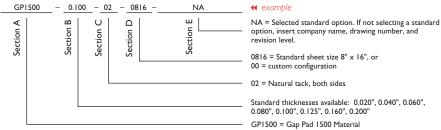
- Telecommunications
- Computer and peripherals
- Power conversion
- RDRAM™ memory modules / chip scale packages
- Areas where heat needs to be transferred to a frame chassis or other type of heat spreader

#### **Configurations Available:**

• Sheet form and die-cut parts

#### **Building a Part Number**

### **Standard Options**



Note: To build a part number, visit our website at www.bergquistcompany.com.

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